



Microelectronic Packaging Solutions For Optimum Performance

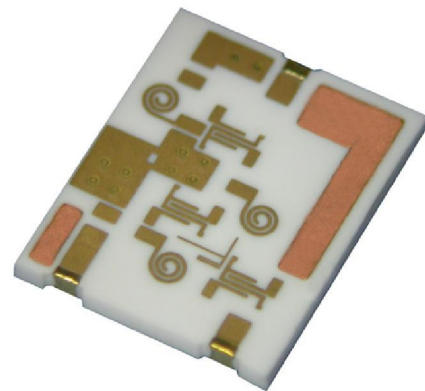
FOR IMMEDIATE RELEASE

Remtec's New Fine-Line Capability

Remtec Adds Capability Combining Etchable Conductor Circuitry with PCTF technology for Manufacture of Fine-Line Ceramic Substrates and Packages

Norwood, MA. January 10, 2007 Remtec, the leading manufacturer of Plated Copper On Thick Film (PCTF®) ceramic substrates and packages, has announced the development of a new etchable materials capability that permits circuit designers to integrate more functions and improve performance while reducing package size. President Nahum Rapoport said "Now designers can select the most cost effective combination of PCTF® metalization options, such as etchable conductors, screen printable thickfilms and plated copper, solid plugged via holes, at a cost significantly lower than comparable thinfilm circuits".

Using this new Remtec capability, microcircuit designers can achieve the performance of thinfilm products with a number of added features: better power dissipation, ability for a direct pc board mount, and an wide resistor range. Engineers can achieve a greater circuit density and more product features by using high resolution conductor lines and spaces with a width of .002". Line definition and tolerances of $\pm .0002$ " assure high frequency performance to 32 GHz and higher, according to Rapoport.



Remtec's advanced PCTF technology enables designers to add significant value by combining a number of ceramic interconnect techniques on a single ceramic substrate. Thickfilm conductors, multilayers, integrated resistors, capacitors and inductors, .004" thick copper, have all become standard features of PCTF® metalization. Remtec is unique in offering this range of solutions.

To greatly improve power dissipation and electrical performance, circuit designers can also take advantage of Remtec's PowerPlugs - hermetic (to 10^{-8}) thermal vias - with thermal conductivity greater than 200 W/°Cxm, electrical resistance less than .5 m Ω , and thermal resistance below 2°C/W.

Microcircuitry produced by Remtec's volume manufacturing process is inherently less expensive than comparable thinfilm circuitry and provides more added value features. Remtec also controls quality and maintains low upfront costs since all design and manufacturing operations are completed in house.

Remtec provides microelectronic packaging solutions for power electronics, telecommunication industry including wireless, broadband, cable TV and satellite communication as well as high reliability electronics, sensors, power supplies, dc/dc converters, bio-medical instrumentation and other electronics applications. Since 1990, the company has expanded to two facilities with 30,000 square feet. The company has over 40 employees and is ISO-9000 Certified.

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